Product specification

Product:	Media slurry
Part number:	07H-1805

Application scope :
This slurry is suitable for the outer layer encapsulation of thick film circuits.

Usage conditions：

Substrate	Thick film circuit, alumina ceramic
Usage method	Printing, 200-250mesh
Leveling	Smooth at room temperature for 5-10 minutes (adjust time as needed)
Curing conditions	Bake in an oven at 100-150°C for 10-15 minutes (if the temperature is below 300°C, adjust the baking time according to actual conditions).
Firing Condition	Sintering in a tunnel furnace under air atmosphere at a peak temperature of 850°C (recommended) for 10 minutes.
Thinner	ST-1001

Characteristics：

1. Paste Characteristics：

Characteristic		Standard	Test method and conditions
1	Fineness	≤8μm	FOG test
2	Viscosity	100~200Pa.s	Brookfield HBT viscometer (Rotor SC4-14/6R), 10 rpm, 25±1°C
3	Appearance	Transparent, black, blue, green	

2. Characteristics after curing：

Under 1 sintering conditions，Check fired film produced under the conditions specified in 1），

Characteristics		Standard	Test method and conditions
4	Appearance	Compact and dense	目测&显微镜 Visual & microscope

Save conditions and validity period :
The product should be stored in a sealed environment at 5-15°C.The shelf life is 1 year from the date of shipment.

Packaging method：
Standard packaging: 1000g per can. Samples are available in 200g small cans.